

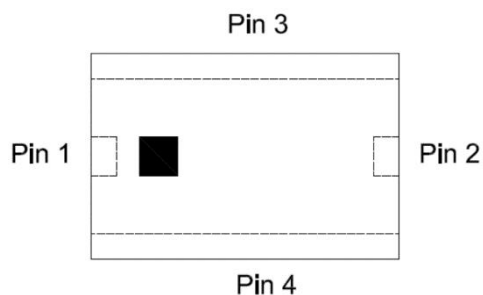
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

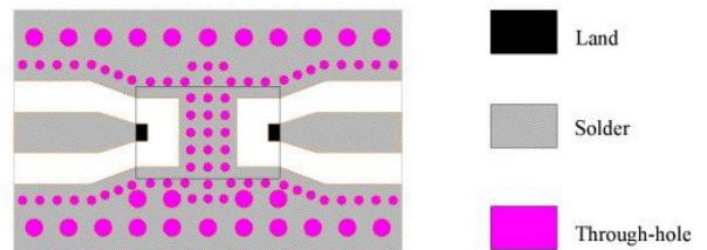
NO.	Parameter	Frequency (MHz)	SPC	
			Min.	Max.
1	Insertion Loss (dB)	1300~2300		1.5
2	Attenuation (dBC)	2500~3000	27	
3	VSWR	1300~2300		1.6
4	Phase consistency (°)	1300~2300		±5
5	In/Output Impedance (Ω)		50	

Construction



PIN	Connection
1	Input Port
2	Output Port
3	GND
4	GND

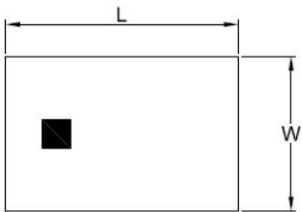
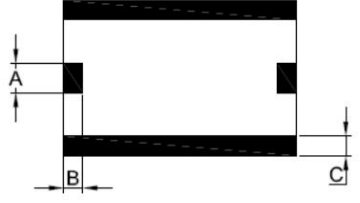

Mounting Considerations



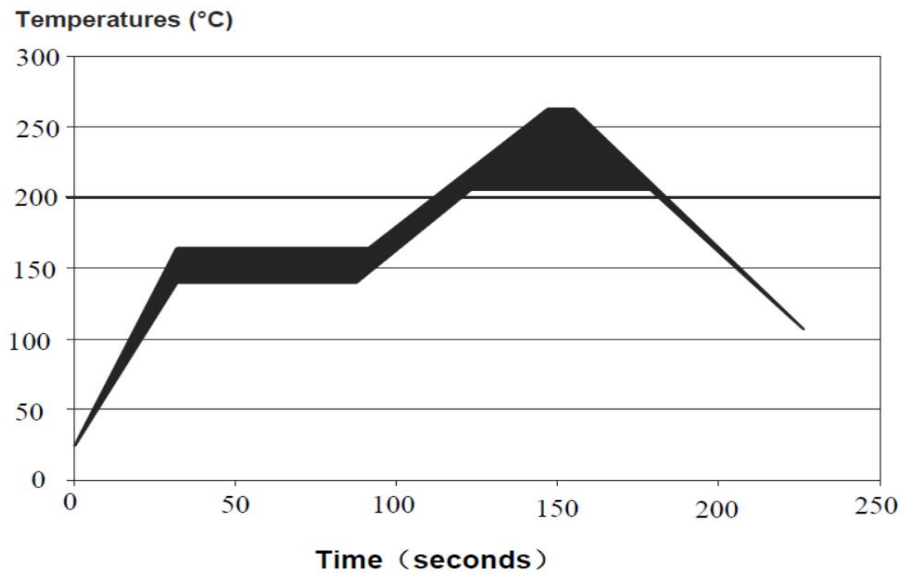
Unit: mm

Line width to be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness

Dimensions

Figure	Symbol	Dimension (mm)
<p>Top view</p>  <p>Bottom view</p>  <p>Side view</p> 	L	5.0±0.10
	W	3.2±0.10
	T	1.5±0.10
	A	0.60±0.10
	B	0.40±0.10
	C	0.4±0.10

Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.